EuroTech

Manufacturing Capabilities

Capability	Standard Production	Advanced Capability
Maximum Production Panel Size	610 x 457 mm	610 x 533 mm
Board Thickness	0.25 mm to 5.50 mm Scored: - 0.30 mm to 3.2 mm	0.10 mm to 5.50 mm Scored: - 0.30 mm to 3.2 mm
Minimum Aspect Ratio	Through Hole: - 10: 1 Blind Hole: - 1: 1	Through Hole: - 16: 1 Blind Hole: - 1:1
Multilayer	Maximum: - 24 layers	Maximum: - 48 layers
Core Thickness	Minimum: - 0.05 mm Maximum: - 2.40 mm	Minimum: - 0.05 mm Maximum: - 5.5 mm
Copper Thickness	Inner: - 18 µm | 35 µm | 50µm Outer: - 12 µm | 18 µm | 35 µm | 70 µm | 105 µm	Other thicknesses available on request
Copper Plating	Minimum: - 25 µm Maximum: - 50 µm	Minimum: - 25 µm Maximum: - 210 µm
Conductor Width / Spacing	Minimum: - 0.075 mm / 0.075 mm	Minimum: - 0.050 mm / 0.050 mm
Annular Ring	Minimum above finished hole size: 0.075mm	Inner Layer: - From 0.050 mm Outer Layer: - From 0.050 mm
Inner Layer Clearances	Minimum clearance from copper plane to plated or non-plated hole: 0.25mm	Minimum clearance from copper plane to plated or non-plated hole: 0.2mm
Profile Clearances	Minimum clearance from copper plane to circuit profile (Routed): 0.20mm Minimum clearance from copper plane to score centre line: 0.5mm	Minimum clearance from copper plane to circuit profile (Routed): 0.15mm Minimum clearance from copper plane to score centre line: 0.5mm

Product Range

Circuit Board	Description
Rigid	Multilayer, Double and Single sided.
Mixed material builds	An advanced rigid board with varying layers of circuits consisting of multiple board materials and thickness
Polyimide	Advanced material with exceptional thermal and dielectric properties
PTFE	Advanced material with outstanding dielectric properties used for RF/Microwave applications
Insulated Metal Substrates (IMS)	Materials designed to aid heat dissipation
Flex	Multilayer, Double and Single sided
Flex Rigid	PCBs with both Flex and Rigid elements

Technology

Technology	Description
Blind Vias	Drilled holes within a multilayer PCB connecting the outer layer to one or more inner layers
Buried Vias	Drilled holes within a multilayer PCB connecting inner layers
Resin Filled and Plugged vias	IPC types III, IV, V and VI
Capped Vias	Resin filled and plated over (IPC type VII)

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Surface Finishes

Metal Finish	In-House / Sub-Contract	Typical Thickness
Electroless Nickel Immersion Gold (ENIG)	In-House	Ni 4µm – 6µm Au 0.05µm – 0.1µm
Electroless Nickel Electroless Palladium Immersion Gold (ENEPIG)	In-House / Sub-Contract	Ni 3µm – 5µm Pd 0.1µm – 0.5µm Au 0.025µm – 0.05µm
Electroplate Gold (Hard) Over Nickel	In-House	Ni 1.0 - 6.0µm Au 1.0µm – 3.0µm
Electroless Gold (Soft) Direct Over Copper	In-House	Au 0.05µm – 1.0µm
Immersion Silver	In-House	0.1µm – 0.25µm
Immersion Tin	Sub-Contract	Sn 1.0µm – 1.1µm
Hot Air Solder Level (HASL)	In-House	10µm – 25µm
Lead-Free Hot Air Solder Level In-house	In-house	10µm – 25µm
Organic Solderability Preservative (OSP)	In-House	0.2µm
Silver Ink	In-House	
Carbon Ink	In-House	
Solder mask	In house – Range of colours and finishes available	